



Material Content Data Sheet



Sales Product Name				SAK-TC299TP-128F300N BC		Issued		25. January 2018	
MA#				MA001680362					
Package				PG-LFBGA-516-5		Weight*		1988.44 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	36.614	1.84	1.84	18413	18413	
wire	noble metal	palladium	7440-05-3	0.023	0.00		12		
	non noble metal	copper	7440-50-8	2.308	0.12	0.12	1161	1173	
encapsulation	organic material	carbon black	1333-86-4	1.679	0.08		844		
	plastics	epoxy resin	-	115.857	5.83		58265		
	inorganic material	silicondioxide	60676-86-0	722.009	36.32	42.23	363103	422212	
substrate	inorganic material	bariumsulfate	7727-43-7	23.317	1.17		11726		
	plastics	acrylic resin	-	26.985	1.36		13571		
	inorganic material	Metal Hydroxide	-	32.274	1.62		16231		
	inorganic material	silicondioxide	60676-86-0	102.202	5.14		51398		
	plastics	epoxy resin	-	192.704	9.69		96912		
	inorganic material	glass fibre	-	225.920	11.36		113616		
	non noble metal	copper	7440-50-8	248.966	12.52	42.86	125206	428660	
plating	noble metal	gold	7440-57-5	1.626	0.08		818		
	non noble metal	nickel	7440-02-0	1.626	0.08	0.16	818	1636	
solderball	noble metal	silver	7440-22-4	8.700	0.44		4375		
	non noble metal	tin	7440-31-5	239.863	12.06	12.50	120628	125003	
glue	plastics	epoxy resin	-	1.443	0.07		726		
	noble metal	silver	7440-22-4	4.328	0.22	0.29	2177	2903	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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